

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3	cluster same (polish\$3 planariz\$4) same (electroless with plat\$3)	US-PGPUB; USPAT	OR	ON	2004/11/05 17:39
S2	12	c23c016\$.ipc. and ((polish\$3 planariz\$4) same (electroless with plat\$3))	US-PGPUB; USPAT	OR	ON	2004/11/05 17:41
S3	3	c23c016\$.ipc. and ((polish\$3 planariz\$4) same (electroless with plat\$3))	EPO; JPO; DERWENT	OR	ON	2004/11/05 17:42
S4	0	(multi\$1chamber (multi with chamber) cluster) and ((polish\$3 planariz\$4) and (electroless with plat\$3))	EPO; JPO; DERWENT	OR	ON	2004/11/05 17:43
S5	188	(multi\$1chamber (multi with chamber) cluster) and ((polish\$3 planariz\$4) and (electroless with plat\$3))	US-PGPUB; USPAT	OR	ON	2004/11/05 17:44
S6	3	(multi\$1chamber (multi with chamber) cluster) same ((polish\$3 planariz\$4) same (electroless with plat\$3))	US-PGPUB; USPAT	OR	ON	2004/11/05 17:45
S7	149	(118/719.ccls. 156/345.31.ccls. 156/345.32.ccls.) and (polish\$3 planariz\$4)	US-PGPUB; USPAT	OR	ON	2004/11/05 17:49
S8	9	(118/719.ccls. 156/345.31.ccls. 156/345.32.ccls.)and (electroless with plat\$3)	US-PGPUB; USPAT	OR	ON	2004/11/12 11:25
S9	2	(118/719.ccls. 156/345.31.ccls. 156/345.32.ccls.)and komino. in.	US-PGPUB; USPAT	OR	ON	2004/11/05 17:47
S10	5	(118/719.ccls. 156/345.31.ccls. 156/345.32.ccls.) and (cluster same (polish\$3 planariz\$4))	US-PGPUB; USPAT	OR	ON	2004/11/05 18:00
S11	1	("5820679").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/05 18:00
S12	1	("5695564").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/11/05 17:24
S13	33	(204/298.25.ccls. 204/298.35.ccls.) and (plat\$3 and polish\$3)	US-PGPUB; USPAT	OR	ON	2004/11/05 17:25
S14	42	(204/298.25.ccls. 204/298.35.ccls.) and (plat\$3 and (polish\$3 planariz\$5))	US-PGPUB; USPAT	OR	ON	2004/11/05 17:27
S15	4	(118/719.ccls. 156/345.31.ccls. 156/345.32.ccls.) and (polish\$3 planariz\$4) and (electroless with plat\$3)	US-PGPUB; USPAT	OR	ON	2005/03/10 17:27
S19	1	(118/719.ccls. 156/345.31.ccls. 156/345.32.ccls. 204/298.25.ccls. 204/298.35.ccls.) and (bevel\$3 with etch\$3 with (edge peripher\$3))	US-PGPUB; USPAT	OR	ON	2004/11/12 11:27
S20	370	(bevel\$3 with etch\$3 with (edge peripher\$3))	US-PGPUB; USPAT	OR	ON	2004/11/12 11:27
S21	27	(118/715-733.ccls. 156/345\$.ccls.) and (bevel\$3 with etch\$3 with (edge peripher\$3))	US-PGPUB; USPAT	OR	ON	2004/11/12 13:00
S23	1	("6267853").PN.	US-PGPUB; USPAT	OR	OFF	2004/11/12 13:00
S24	1	("6267853").PN.	US-PGPUB; USPAT	OR	OFF	2004/11/12 18:05
S25	941	kimura-norio.in. mishima-koji.in. kunisawa-junji.in. odagaki-mitsuko.in. makino-natsuki.in. tsujimura-manabu.in. inoue-hiroaki.in. nakamura-kenji.in. matsumoto-moriji.in. matsuda-tetsuo.in. kaneko-hisashi.in. morita-toshiyuki.in. hayasaka-nobuo.in. okumura-katsuya.in.	US-PGPUB; USPAT	OR	ON	2005/03/20 22:23
S26	182	S25 and plating	US-PGPUB; USPAT	OR	ON	2004/11/12 18:09
S27	196	S25 and (plating plated)	US-PGPUB; USPAT	OR	ON	2004/11/12 18:10
S28	173	S25 and (plating plated) and (transfer\$4 transport\$4 convey\$4 (sens\$3 detect\$3 monitor\$3 measur\$4))	US-PGPUB; USPAT	OR	ON	2004/11/12 18:42
S29	1	("6610151").PN.	US-PGPUB; USPAT	OR	OFF	2004/11/12 18:42

S30	0	"09742386"	US-PGPUB; USPAT	OR	ON	2004/11/29 12:41
S31	1	"09/742,386"	US-PGPUB; USPAT	OR	ON	2004/11/29 12:41
S32	1	118/719.ccls. and komino.in.	US-PGPUB; USPAT	OR	ON	2005/03/10 17:18
S33	1	(118/719.ccls. 156/345.31.ccls. 156/345.32.ccls.) and (inspect\$3 with align\$4 with chamber)	US-PGPUB; USPAT	OR	ON	2005/03/10 17:47
S34	26	((wafer substrate semiconductor workpiece) with inspect\$3 with align\$4 with chamber)	US-PGPUB; USPAT	OR	ON	2005/03/10 17:28
S35	17	(US-20010024691-\$ or US-20010028924-\$ or US-20010043989-\$ or US-20030010449-\$ or US-20030102084-\$).did. or (US-5695564-\$ or US-5820679-\$ or US-6267853-\$ or US-6610151-\$ or US-6695921-\$ or US-6780787-\$ or US-5769952-\$ or US-5766360-\$ or US-6084419-\$ or US-6366688-\$ or US-6841485-\$).did. or (JP-02279278-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2005/03/10 17:39
S36	2	(118/719.ccls. 156/345.31.ccls. 156/345.32.ccls.) and (bevel\$3 with etch\$3)	US-PGPUB; USPAT	OR	ON	2005/03/10 17:47
S37	36	(156/345.\$ccls.) and (bevel\$3 with etch\$3)	US-PGPUB; USPAT	OR	ON	2005/03/10 17:58
S38	1	("6423642").PN.	US-PGPUB; USPAT	OR	OFF	2005/03/10 17:58
S39	1	09/742,386	US-PGPUB; USPAT	OR	ON	2005/03/20 21:09
S40	1	("6267853").PN.	US-PGPUB; USPAT	OR	OFF	2005/03/20 21:09
S41	1	("5083364").PN.	US-PGPUB; USPAT	OR	OFF	2005/03/20 22:24
S42	25	(US-20010024691-\$ or US-20010028924-\$ or US-20010043989-\$ or US-20020050322-\$ or US-20030010449-\$ or US-20030102084-\$ or US-20040231794-\$ or US-20040241998-\$).did. or (US-4968375-\$ or US-5695564-\$ or US-5766360-\$ or US-5769952-\$ or US-5820679-\$ or US-6084419-\$ or US-6267853-\$ or US-6309981-\$ or US-6333275-\$ or US-6366688-\$ or US-6423642-\$ or US-6537416-\$ or US-6610151-\$ or US-6695921-\$ or US-6780787-\$ or US-6841485-\$).did. or (JP-02279278-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2005/03/21 00:41
S43	16	S42 and align\$4	US-PGPUB; USPAT; DERWENT	OR	ON	2005/03/21 00:10
S44	873	electroplat\$3 and (seal\$3) and (anode with above)	US-PGPUB; USPAT; DERWENT	OR	ON	2005/03/21 00:43
S45	858	electroplat\$3 and (seal\$3) and (anode with above)	US-PGPUB; USPAT	OR	ON	2005/03/21 00:43
S46	258	electroplat\$3 and ((seal\$3) with (edge periph\$5)) and (anode with above)	US-PGPUB; USPAT	OR	ON	2005/03/21 00:43
S47	100	electroplat\$3 and ((seal\$3) with (edge periph\$5) with (substrate semiconductor workpiece)) and (anode with above) and ((lift\$3 rais\$3 lower\$3) with position\$3 with (substrate semiconductor workpiece))	US-PGPUB; USPAT	OR	ON	2005/03/21 00:52
S48	98	S47 and ((substrate wafer) with fac\$3)	US-PGPUB; USPAT	OR	ON	2005/03/21 00:52
S49	84	S47 and ((substrate wafer) with fac\$3 with up\$5)	US-PGPUB; USPAT	OR	ON	2005/03/21 00:52